

### Abstract

5 An interconnect is provided for making electrical  
connections with a semiconductor die. The interconnect  
includes a substrate having integrally formed contact  
members, configured to electrically contact corresponding  
contact locations on the die. The interconnect also includes  
10 a pattern of conductors formed separately from the substrate,  
and then bonded to the substrate, in electrical communication  
with the contact members. The conductors can be mounted to a  
multi layered tape similar to TAB tape, or alternately bonded  
directly to the substrate. In addition, each conductor can  
15 include an opening aligned with a corresponding contact  
member, and filled with a conductive material, such as a  
conductive adhesive or solder. The conductive material  
electrically connects the contact members and conductors, and  
provides an expansion joint to allow expansion of the  
conductors without stressing the contact members. Also  
20 provided are a system for testing dice that includes the  
interconnect, and a system for testing wafers wherein the  
interconnect is formed as a probe card.

09302576-043099